

NEWS RELEASE

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Indium Corporation to Share Expertise on Thermal Interface Materials at Upcoming INEMI Webinar

A technical presentation on thermal interface materials (TIMs) will be featured at an upcoming webinar organized by the [International Electronics Manufacturing Initiative \(INEMI\)](#) and hosted by Masahiro Tsuruya on November 25. [Indium Corporation's](#) R&D Manager – TIM Group, Dr. Jie Geng, will share insights into the evolving landscape of TIM technology and its critical role in supporting next-generation electronics.

Dr. Geng's presentation, [*Cooling the Future: TIM Strategies for High-Density AI and HPC Platforms*](#), will examine how advanced thermal interface materials (TIMs) enable reliable heat management in artificial intelligence (AI) and high-performance computing (HPC) systems operating at extreme power densities. As AI and HPC continue to push the limits of power and performance, managing the resulting heat has become one of the most critical design challenges. This webinar will explore the vital role TIMs play in ensuring stable thermal performance in next-generation graphics processing units (GPUs) and processors operating at power levels exceeding 1000W per device.



“We’ll examine the characteristics of leading TIM technologies—including greases, phase-change materials, liquid metal alloys, and indium-based metal TIMs—and discuss how each performs under harsh environmental conditions such as thermal cycling, vibration, and high humidity,” Dr. Geng shared. “This event will also showcase hybrid TIM stacks, which combine multiple materials to execute optimal heat transfer, long-term stability, and mechanical compliance.”

Attendees will gain valuable insights into key selection criteria, real-world performance comparisons across leading TIM types and material configurations, and emerging material innovations that enable AI and HPC hardware to operate safely and efficiently under extreme workloads.

Dr. Geng joined Indium Corporation in 2017 and has more than 20 years of experience in materials science research and engineering. He holds a doctorate in metallurgy, a master's degree in materials science, and a bachelor's degree in materials science and engineering with notable contributions to the development of Indalloy[®] 292 and Durafuse[®] HR.

The webinar will take place on Tuesday, November 25, at EDT 9:00 a.m. Registration is available [online](#).

Leveraging decades of experience, Indium Corporation remains at the forefront of thermal interface materials innovation, enabling high-performance electronics to operate safely and efficiently. To learn more about Indium Corporation's innovative TIMs solutions, visit <https://www.indium.com/products/thermal-interface-materials/>.

About Indium Corporation

Indium Corporation[®] is a premier materials refiner, smelter, manufacturer, and supplier to the global electronics, semiconductor, thin-film, and thermal management markets. Products include solders and fluxes; brazes; thermal interface materials; sputtering targets; indium, gallium, germanium, and tin metals and inorganic compounds; and NanoFoil[®]. Founded in 1934, the company has global technical support and factories located in China, Germany, India, Malaysia, Singapore, South Korea, the United Kingdom, and the U.S.

For more information about Indium Corporation, visit www.indium.com or email jhuang@indium.com. You can also follow our experts, From One Engineer To Another[®] (#FOETA), at www.linkedin.com/company/indium-corporation/.

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